

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10540992			
<b>Filing Date:</b>	05-Jun-2006			
<b>Title of Invention:</b>	Chemical-mechanical-polishing slurry composition, method for planarizing surface of semiconductor device using the same, and method for controlling selection ratio of slurry composition			
<b>First Named Inventor/Applicant Name:</b>	Jea Gun Park			
<b>Filer:</b>	Robert Charles Friedt Perez/Febes Iazo			
<b>Attorney Docket Number:</b>	061063-0316598			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Request for continued examination	1801	1	810	810
<b>Total in USD (\$)</b>				<b>810</b>